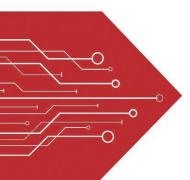
# MSKSEMI















**ESD** 

**TVS** 

**TSS** 

MOV

**GDT** 

**PLED** 

Product data sheet

www.msksemi.com



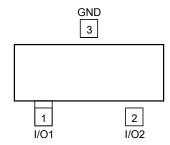








#### Circuit diagram

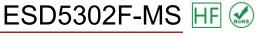


#### **Features**

- Stand-off voltage: 5V Max
- Transient protection for each line according to IEC61000-4-2 (ESD): ±20kV (contact and air discharge) IEC61000-4-4 (EFT): 40A (5/50ns) IEC61000-4-5 (surge): 4A (8/20µs)
- Ultra-low capacitance:  $C_J = 0.4pF$  typ.
- Ultra-low leakage current: I<sub>R</sub> <1nA typ.
- Low clamping voltage:  $V_{CL} = 20V @ I_{PP} = 16A(TLP)$
- Solid-state silicon technology

## **Applications**

- USB 2.0 and USB 3.0
- HDMI 1.3 and HDMI 1.4
- SATA and eSATA
- DVI
- **IEEE 1394**
- **PCI Express**
- Portable Electronics
- Notebooks







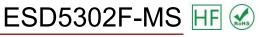
Parameter	Symbol	Rating	Unit	
Peak pulse power (t <sub>p</sub> = 8/20µs)	$P_{pk}$	60	W	
Peak pulse current (t <sub>p</sub> = 8/20µs)	I <sub>PP</sub>	4	А	
ESD according to IEC61000-4-2 air discharge	V	±20	kV	
ESD according to IEC61000-4-2 contact discharge	$ V_{ESD}$	±20		
Junction temperature	TJ	125	°C	
Operating temperature	T <sub>OP</sub>	-40~85	°C	
Lead temperature	TL	260	°C	
Storage temperature	T <sub>STG</sub>	-55~150	°C	

# Electrical characteristics (T<sub>A</sub>=25 °C, unless otherwise noted)

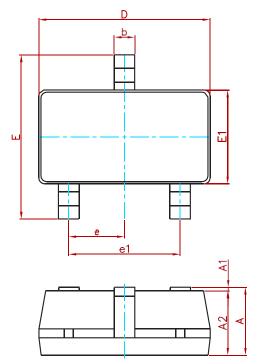
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Reverse maximum working voltage	$V_{RWM}$				5.0	V
Reverse leakage current	I <sub>R</sub>	V <sub>RWM</sub> = 5V		<1	100	nA
Reverse breakdown voltage	$V_{BR}$	I <sub>T</sub> = 1mA	7.0	8.0	9.0	V
Forward voltage	V <sub>F</sub>	I <sub>T</sub> = 10mA	0.6	0.9	1.2	V
Clamping voltage 1)	V <sub>CL</sub>	I <sub>PP</sub> = 16A, t <sub>p</sub> = 100ns		20		V
Dynamic resistance 1)	R <sub>DYN</sub>			0.65		Ω
Clamping voltage <sup>2)</sup>	V <sub>CL</sub>	$I_{PP}$ = 1A, $t_p$ = 8/20 $\mu$ s			11	V
		$I_{PP} = 4A, t_p = 8/20 \mu s$			15	V
Junction capacitance	CJ	V <sub>R</sub> = 0V, f = 1MHz Any I/O pin to GND		0.40	0.65	pF
		V <sub>R</sub> = 0V, f = 1MHz Between any I/O pin		0.25	0.40	pF

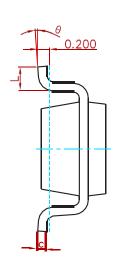
- 1) TLP parameter:  $Z_0 = 50 \Omega$ ,  $t_p = 100$ ns,  $t_r = 2$ ns, averaging window from 60ns to 80ns.  $R_{DYN}$  is calculated from 4A to 16A.
- 2) According to IEC61000-4-5.





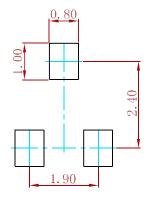
#### **PACKAGE MECHANICAL DATA**





Cumahal	Dimensions In Millimeters		Dimension	s In Inches	
Symbol	Min.	Max.	Min.	Max.	
А	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E1	1.500	1.700	0.059	0.067	
E	2.650	2.950	0.104	0.116	
е	0.950(	BSC)	0.037	(BSC)	
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
0	0°	8°	0°	8°	

## **Suggested Pad Layout**



- 1.Controlling dimension:in millimeters. 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

## **REEL SPECIFICATION**

P/N	PKG	QTY
ESD5302F-MS	SOT-23	3000



Semiconductor

#### Compiance

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